



FG484 - Pb/Sn SOLDER BALLS  
 FGG484 - Sn/Ag/Cu

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.00	2.20	2.60	3
A <sub>1</sub>	0.35	0.50	0.60	
D/E	23.00 BSC			2
D <sub>1</sub> /E <sub>1</sub>	21.00 REF			
e	1.00 BSC			
Øb	0.50	0.60	0.70	
aaa	<del>xxx</del>	<del>xxx</del>	0.20	
ccc	<del>xxx</del>	<del>xxx</del>	0.35	
ddd	<del>xxx</del>	<del>xxx</del>	0.30	
eee	<del>xxx</del>	<del>xxx</del>	0.10	
M	22			

## NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAJ-1 (DEPOPULATED)

## Revision History

The following table shows the revision history for this document.

Date	Version	Revision
03/01/05	1.0	Initial Xilinx release.
12/15/08	1.1	Added "a" min. 2.00 and max. 2.20 on the dimension table and updated the notes section.